

Title (en)

METHOD FOR PRODUCING BRIDGE MODULES

Title (de)

VERFAHREN ZUR HERSTELLUNG VON MODULBRÜCKEN

Title (fr)

PROCEDE DE PRODUCTION DE PONTS DE MODULE

Publication

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Application

EP 04764401 A 20040824

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Abstract (en)

[origin: WO2005022456A1] The invention relates to a method for producing bridge modules (29) for smart labels, enabling the positioning of chip modules (25) on carriers (31) and the bridged conductive connection of connection elements of said chip module (25) to connection elements (30a, 30b) of antenna elements (30) that are located on or in the carriers (31). Said method comprises the following steps: formation (2) of recesses (22) located one behind the other in a continuous carrier strip (21) that can be displaced in a longitudinal direction; positioning (4) of a respective chip module (25) in each recess (22) with the connection elements facing upwards; and application (8) of contact layer strips (27a, 27b) to the connection elements of the chip modules (25) and to a surface of the carrier strip (21) that lies adjacent to the recesses (22) in order to form enlarged contact surfaces.

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